


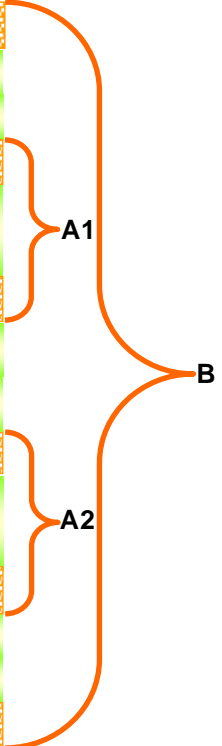








**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**06 105 FR4 35 L20.35 P10\_06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**06\_105\_FR4\_35\_L20.35\_p10\_06**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	35 $\mu$	Copper		
	60 $\mu$	Prepreg		
<b>Layer-2</b>	60 $\mu$	Prepreg		
	35 $\mu$	Copper		
<b>Layer-3</b>	200 $\mu$	L-FR4		
	35 $\mu$	Copper		
<b>Layer-4</b>	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-5</b>	35 $\mu$	Copper		
	200 $\mu$	L-FR4		
<b>Layer-99</b>	35 $\mu$	Copper		
	60 $\mu$	Prepreg		
	60 $\mu$	Prepreg		
	35 $\mu$	Copper		

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